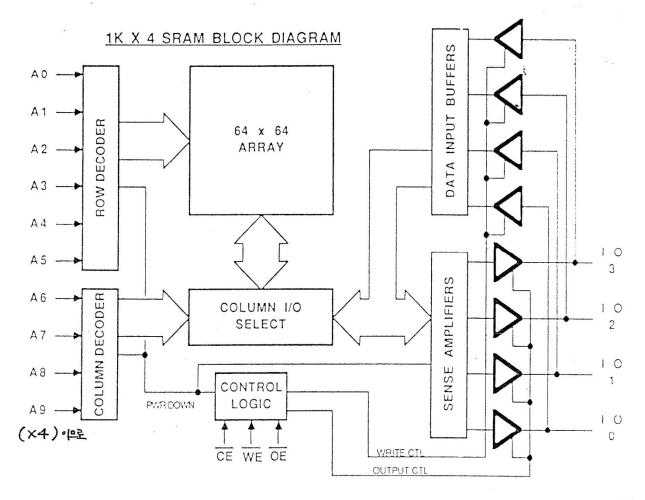
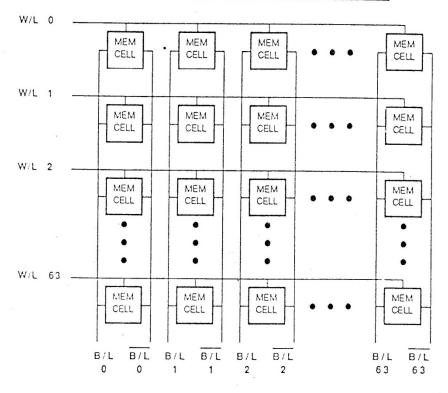
# Static Random Access Memories (sRAM) Instructor - Bruce Bateman, Cypress Semiconductor

- Basic Architecture
- Storage Cell
- Address Decoding
- Data Sensing
- READ/WRITE Control

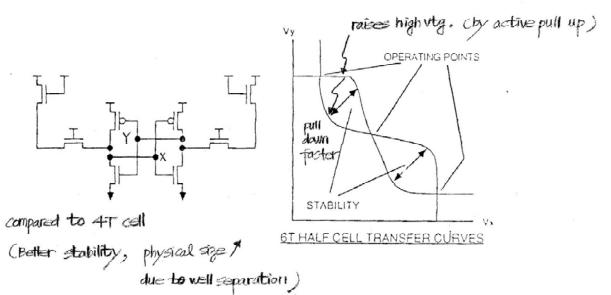


SRAM.

#### 4K SRAM MEMORY ARRAY

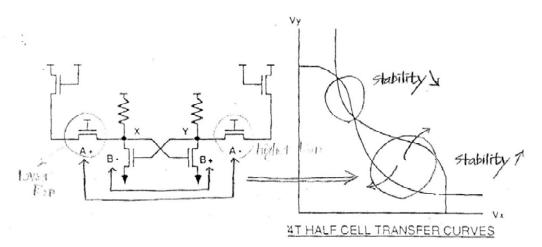


#### 6T MEMORY CELL "READ" STABILITY



SRAMI

#### MEMORY CELL ASYMETRY



#### CAUSES:

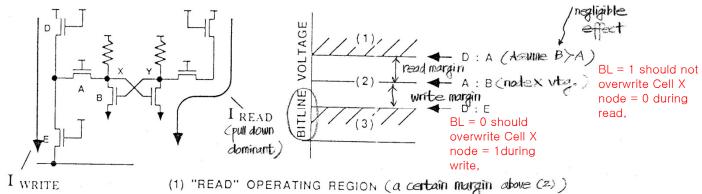
- . DESIGN MISMATCH DIFFERENT LAYOUT/SIZE
- PROCESS MISMATCH VI, CDs, ETC
  ALIGNMENT SENSITIVITY WIDTH, LENGTH

Forting dimension

#### SKIP

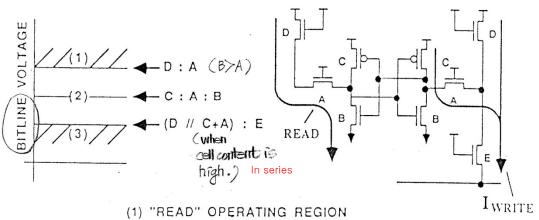
#### 4T MEMORY CELL READ/WRITE OPERATION

#### Imagine voltage divider



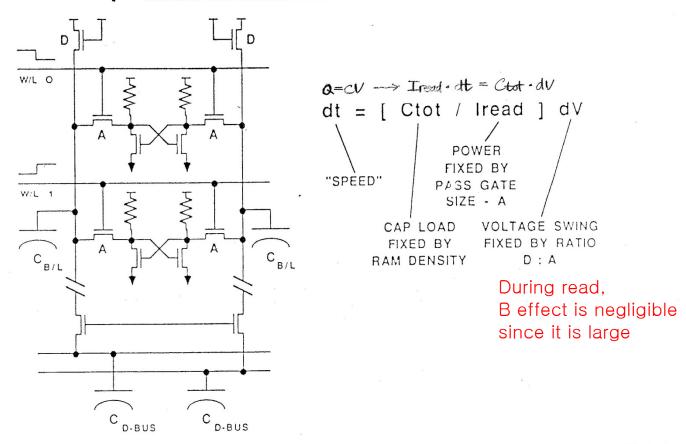
- (1) "READ" OPERATING REGION (a certain margin above (2))
- (2) MEM CELL "TRIP" VOLTAGE
- (3) "WRITE" OPERATING REGION (a certain margin below (2))

#### MEMORY CELL READ/WRITE OPERATION



- (2) MEM CELL "TRIP" VOLTAGE
- (3) "WRITE" OPERATING REGION

#### MEMORY CELL SPEED VR. POWER



### DRAM - Dynamic Random-Access Memory

1988 IEDM Short Course on Microprocessor and Memories

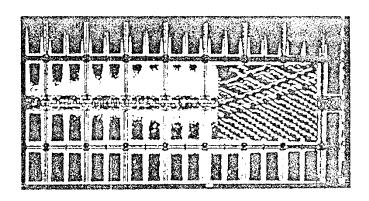
Nicky C.-C. Lu

## 1. DRAM And Its Development

- 1.1 Background And Definition
- 1.2 DRAMs in Systems: Examples
- 1.3 Product Environments And Trends

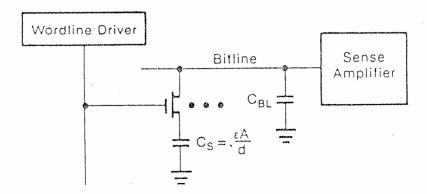
#### DRAM Chip

- Cell Arrays And Peripheral Circuits
- Array Utilization = (Cell Area × Total Bits)/(Chip Area)
- Key: Small Cell Area,



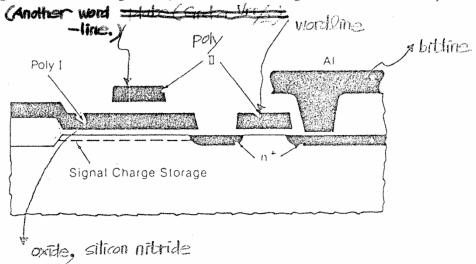
#### One-Transistor Cell

- An Access Transistor Plus A Storage Capacitor
  - Selected By Wordline
  - Signal Developed on Bitline



#### Planar Cell Structure

- Planar Transistor Plus Planar Capacitor in Silicon
- Uses Two Polysilicon Layers
- Storage-Node Leakage Requires Refreshing Data Periodically

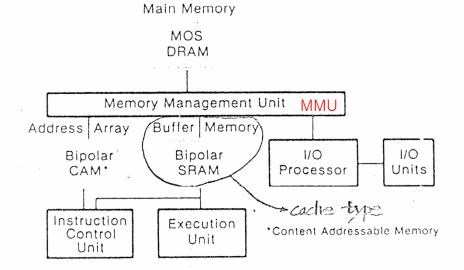


#### **DRAM** Definition

- Randomly Addressable Memory (Versus Serial Memory)
- Electrically Read and Write Data at Will in Any Sequence
- Needs Refresh Periodically
- Volatile (Unless By Battery Backup)

#### DRAM in Mainframe

- Today: ≃1GB (8,000 1Mb DRAM Chips)
- By 1995: ≥64GB (Needs 8,000 64Mb DRAM Chips)



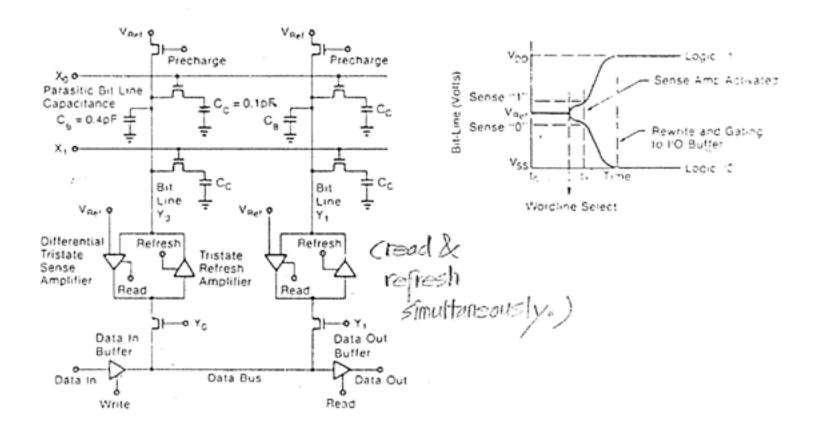
(Figure from Ref. B-6)

Nicky Lu 8/88

### 2. Chip/Circuit Design

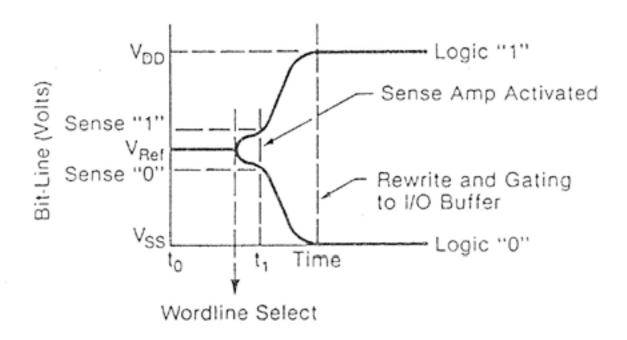
- 2.1 Basic DRAM Operations
- 2.2 Design Example: A 512Kb CMOS High Speed DRAM
- 2.3 Notes on NMOS and BiCMOS DRAMs

### Basic Array Design



(After Ref.)

### Signal Development



### Charge Transfer Ratio Concept (During Read)

• 
$$V_{R}(1) = \frac{C_{s}V(1) + C_{B}V_{ref}}{C_{s} + C_{B}}$$
 (charge sharing)  $C_{s}$ ; cell ap.  
•  $\Delta V_{sen}(1) = V_{R}(1) - V_{ref} = \frac{C_{s}}{C_{s} + C_{B}}$  [V(1) -  $V_{ref}$ ]

•  $\Delta V_{sen}(0) = V_{ref} - V_{R}(0) = \frac{C_{s}}{C_{s} + C_{B}}$  [V<sub>ref</sub> - V(0)]

•  $V_{sen} = \frac{1}{2} [\Delta V_{sen}(1) + \Delta V_{sen}(0)] = \frac{1}{2} \frac{C_{s}}{C_{s} + C_{B}}$  [V(1) - V(0)]

• Transfer Ratio T =  $\frac{C_{s}}{C_{s} + C_{B}}$ 

• Storage Charge Capacity  $Q_s = C_s V_s = 2(C_s + C_B)V_{sen}$ 

### Cell Design Basics

• 
$$V_{sen} + \Delta V = \frac{1}{2(C_S + C_B)} \cdot \frac{\epsilon_A V_S}{d}$$

Where AV: Noise

ε: Dielectric Constants

A: Storage Area

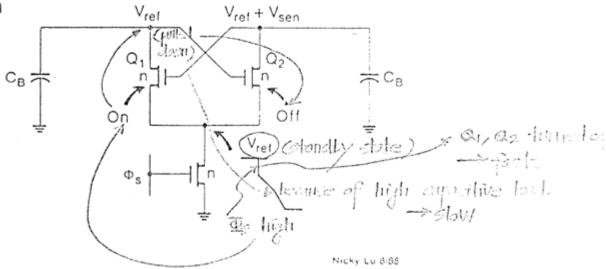
V<sub>S</sub>: Storage Signal

d: Dielectric Thickness

V<sub>s</sub>/d Limited By Maximum Dielectric Strength

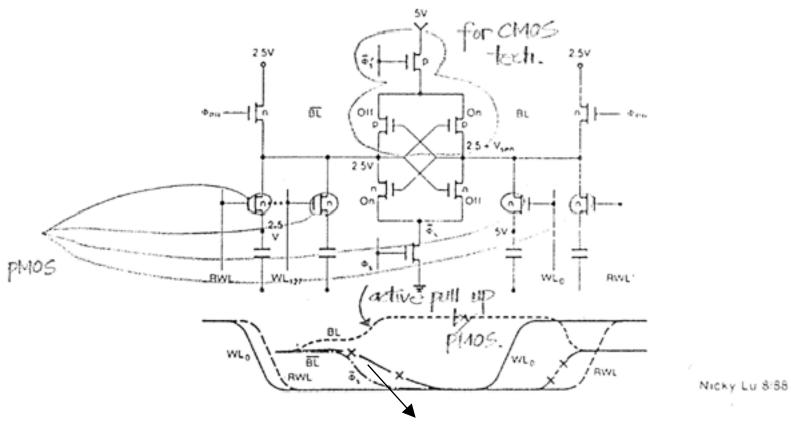
### Cross-Coupled Sense Amplifier

- · Differential Signal Established
- Latching
- Amplification



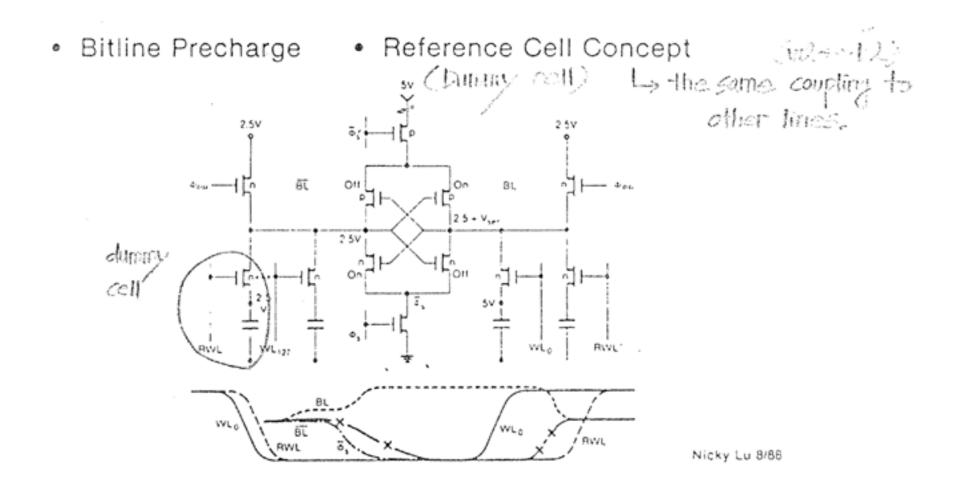
### Sensing Circuits

CMOS Cross-Coupled Latch



Phi pulled down then bit line change

### Sensing Circuits



### Sensing Circuits

• Self Restore • Refresh

Solf Restore • Refresh

The state of the sta

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